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Leybold Mag 400C, 400CT

Technical Specifications

Technical Data		TURBOVAC MAG	
		400 C	400 CT
Inlet flange	DN	100 ISO-K	100 ISO-K
Pumping speed according to PNEUROP			
N ₂	l x s ⁻¹	240 ¹⁾	240 ¹⁾
H ₂	l x s ⁻¹	180 ¹⁾	174 ¹⁾
Speed (high / low)	min ⁻¹	51 600 / 43 860	51 600 / 43 860
Compression ratio			
N ₂		2 x 10 ⁶	2 x 10 ⁶
H ₂		5 x 10 ²	5 x 10 ²
Ultimate pressure according to DIN 28 400 mbar (Torr)		< 10 ⁻⁹ (< 0.75 x 10 ⁻⁹)	< 10 ⁻⁹ (< 0.75 x 10 ⁻⁹)
Max. foreline pressure for N ₂ mbar (Torr)		5 x 10 ⁻¹ (3.75 x 10 ⁻¹)	5 x 10 ⁻¹ (3.75 x 10 ⁻¹)
Recommended forevacuum pump		TRIVAC D 65 BCS Scroll	TRIVAC D 65 BCS Scroll
Run-up time to 95% speed	min	3.5	3.5
forevacuum flange	DN	25 KF	25 KF
Purge / vent port	DN	10 KF	10 KF
Cooling water connections (hose nipple)			
	mm (in.)	7.5 (0.30)	7.5 (0.30)
Weight, approx.	kg (lbs)	16 (35)	16 (35)

Electronic frequency converter : TURBOTRONIK NT 340 MA (120 V)



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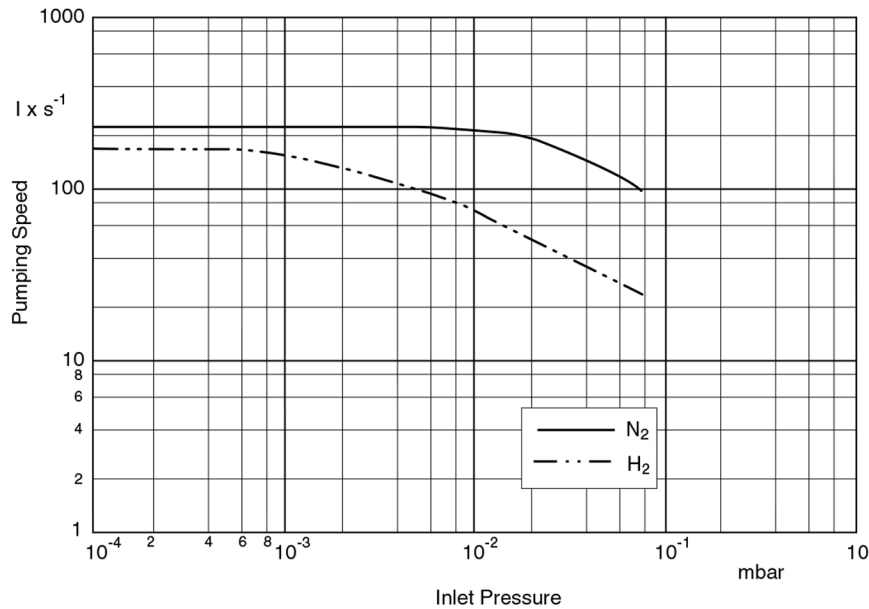
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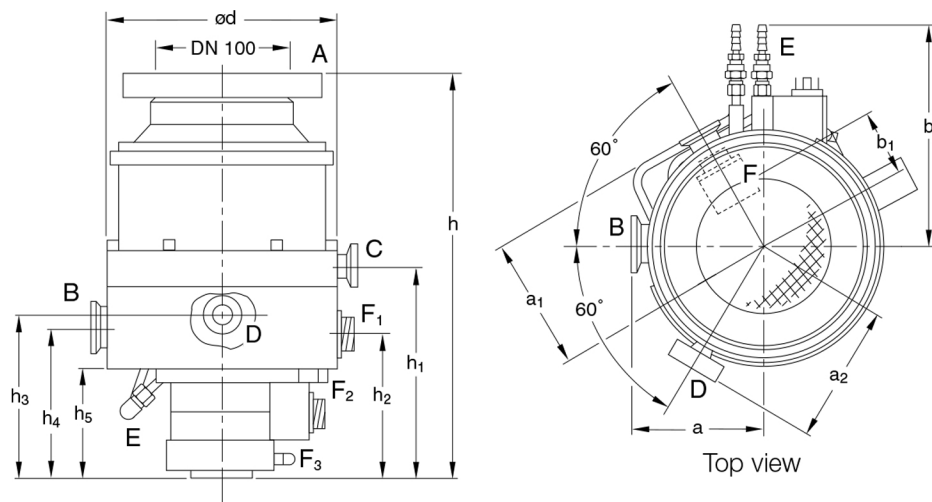
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Pumping Curves



Pumping speed of the TURBOVAC MAG 400 C/CT as a function of the inlet pressure

Dimensions



	a	a ₁	a ₂	b	b ₁	d	h	h ₁	h ₂	h ₃	h ₄	h ₅
mm	100	114	111	186	50	178	300	162	109	123	114	80
in.	3.94	4.49	4.37	7.32	1.97	7.01	11.81	6.38	4.29	4.84	4.49	3.15

Dimensional drawing for the TURBOVAC MAG 400 CT



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Features & Benefits

- magnetic bearing system
- patented KEPLA-COAT® for rotor & stator to prevent corrosion
- low noise & vibration levels
- operation in any orientation
- optimized corrosion-resistant advanced rotor design
- high temperature/stress tolerance material
- temperature management system for etch application
- maintenance free
- optimized vacuum performance
- resistance against corrosive gases
- robust against shock-venting

Applications

- load locks • transfer chambers • all major semiconductor processes (etch, CVD, PVD, ion implantation) • particle accelerators • gas analysis systems • electron beam microscopy • research instruments and systems